

## 6 x 6 Dots Matrix LED Driver IC

# KA32182A Product Brief

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Regarding the specifications of this product, it is considered that you have agreed to the quality level and disclaimer described below.

Support for industry standards and quality standards

<b>Functional safety standards for automobiles ISO26262</b>	<b>No</b>
<b>AECQ-100</b>	<b>No</b>
<b>Market failure rate</b>	<b>50 Fit</b>

Disclaimer

1. When the application system is designed using this IC, please design the system at your own risk. Please read, consider, and apply appropriate usage notes and description in this standard.
2. When designing your application system, please take into the consideration of break down and failure mode occurrence and possibility in semiconductor products. Measures on the systems such as, but not limited to, redundant design, mitigating the spread of fire, or preventing glitch, are recommended in order to prevent physical injury, fire, social damages, etc. in using the Nuvoton Technology Japan Corporation (hereinafter referred to as NTCJ) products.
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4. Please use this IC in compliance with all applicable laws, regulations and safety-related requirements that regulate the inclusion or use of controlled substances, including without limitation, the EU RoHS Directive. NTCJ shall not be held responsible for any damage incurred as a result of this IC being used not in compliance with the applicable laws, regulations and safety-related requirements.
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9. In case of damages, costs, losses, and/or liabilities incurred by NTCJ arising from customer's non-compliance with above from 1 to 8, customer will indemnify NTCJ against every damages, costs, losses and responsibility.

KA32182A Product Brief

## 6 x 6 Dots Matrix LED Driver IC

### FEATURES

- 6 × 6 LED Matrix Driver  
(Total LED that can be driven = 36)
- LED Selectable Maximum Current
- LED Music Synchronizing function
- I<sup>2</sup>C interface (Standard Mode, Fast Mode and Fast Mode Plus)  
(4 Slave address selectable)
- 20 pin Plastic Quad Flat Non-leaded Package (QFN Type)

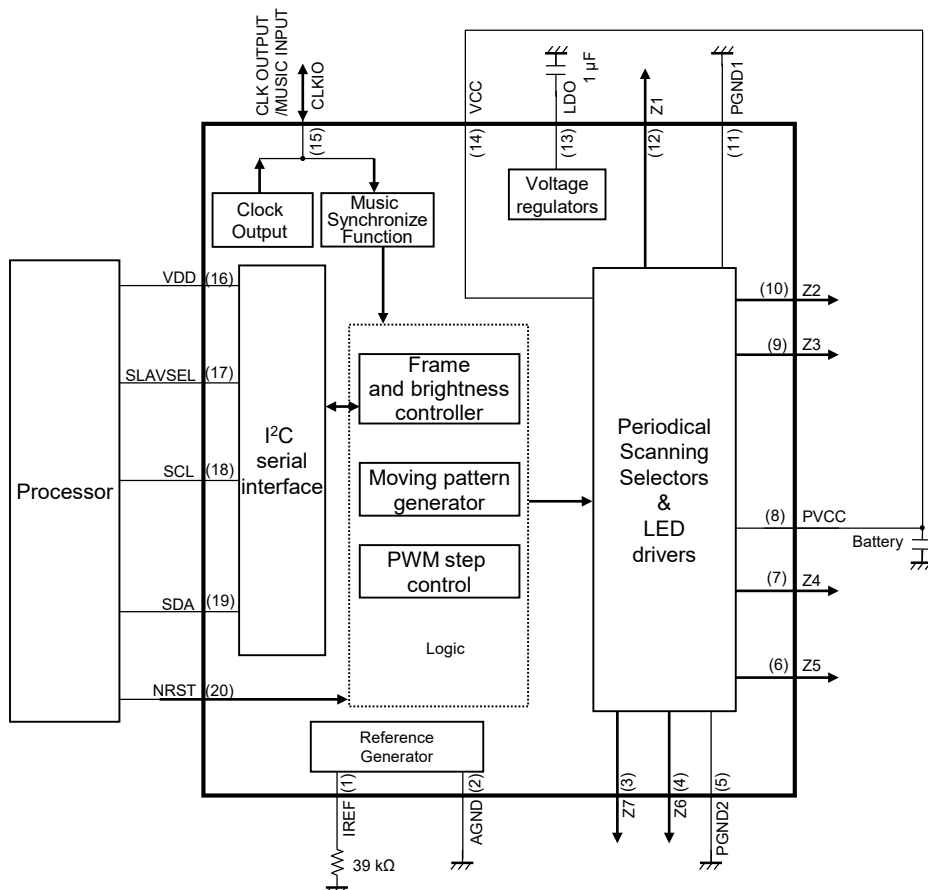
### DESCRIPTION

KA32182A is a 36 dots Matrix LED driver. It can drive up to 12 RGB LEDs.

### APPLICATIONS

- Mobile, Wearable
- Smart Speaker
- PCs
- Game Consoles
- Home Appliances etc.

### TYPICAL APPLICATION



**Note:**

The application circuit is an example. The operation of the mass production set is not guaranteed. Sufficient evaluation and verification is required in the design of the mass production set. The Customer is fully responsible for the incorporation of the above illustrated application circuit in the design of the equipment.

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## ORDERING INFORMATION

Order Number	Feature	Package	Output Supply
KA32182A-VB	LED Driver for Illumination	20 pin QFN	Emboss Taping

## ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Rating	Unit	Note
Supply voltage	$V_{CC_{MAX}}$	6.0	V	*1
	$V_{DD_{MAX}}$	6.0	V	*1
Operating ambience temperature	$T_{opr}$	- 30 to + 85	°C	*2
Operating junction temperature	$T_j$	- 30 to + 125	°C	*2
Storage temperature	$T_{stg}$	- 55 to + 125	°C	*2
Input Voltage Range	$V_{SLAVSEL}, V_{SCL}, V_{SDA}, V_{CLKIO}, V_{NRST}$	- 0.3 to 6.0	V	—
Output Voltage Range	$V_{IREF}, V_{LDO}, V_{CLKIO}, V_{Z1}, V_{Z2}, V_{Z3}, V_{Z4}, V_{Z5}, V_{Z6}, V_{Z7}$	- 0.3 to 6.0	V	—
ESD	HBM	2.0	kV	—

Note: This product may sustain permanent damage if subjected to conditions higher than the above stated absolute maximum rating. This rating is the maximum rating and device operating at this range is not guaranteed as it is higher than our stated recommended operating range. When subjected under the absolute maximum rating for a long time, the reliability of the product may be affected.

\*1:  $V_{CC_{MAX}} = V_{CC} = PV_{CC}$ ,  $V_{DD_{MAX}} = V_{DD}$ .

The values under the condition not exceeding the above absolute maximum ratings and the power dissipation.

\*2: Except for operating ambient temperature, operating junction temperature and storage temperature, all ratings are for  $T_a = 25^{\circ}\text{C}$ .

## POWER DISSIPATION RATING

Package	$\theta_{JA}$	$P_D (T_a=25^{\circ}\text{C})$	$P_D (T_a=85^{\circ}\text{C})$
QFN 20L (3x4x0.8mm <sup>3</sup> , Lead Pitch 0.4mm)	194.0 °C /W	0.515 W	0.206 W

Note: For the actual usage, please refer to the  $P_D$ - $T_a$  characteristics diagram in the package specification, follow the power supply voltage, load and ambient temperature conditions to ensure that there is enough margin and the thermal design does not exceed the allowable value.



### CAUTION

Although this IC has built-in ESD protection circuit, it may still sustain permanent damage if not handled properly. Therefore, proper ESD precautions are recommended to avoid electrostatic damage to the MOS gates.

**RECOMMENDED OPERATING CONDITIONS**

Parameter	Symbol	Min.	Typ.	Max.	Unit	Note
Supply voltage range	$V_{CC}$	3.1	3.6	5.5	V	—
	$V_{DD}$	1.7	1.85	5.5	V	—
Input Voltage Range	$V_{SLAVSEL}, V_{SCL}, V_{SDA}, V_{CLKIO}$	-0.3	—	$V_{DD} + 0.3$	V	*1
	$V_{NRST}$	-0.3	—	$V_{CC} + 0.3$	V	*1
Output Voltage Range	$V_{IREF}, V_{LDO}, V_{CLKIO}, V_{Z1}, V_{Z2}, V_{Z3}, V_{Z4}, V_{Z5}, V_{Z6}, V_{Z7}$	-0.3	—	$V_{CC} + 0.3$	V	*1

Note: Voltage values, unless otherwise specified, are with respect to GND. GND is voltage for GND.

$V_{CC}$  is voltage for VCC.  $V_{DD}$  is voltage for VDD.

Do not apply external currents or voltages to any pin not specifically mentioned.

\*1 :  $(V_{CC} + 0.3)$  V must not exceed 6 V.  $(V_{DD} + 0.3)$  V must not exceed 6 V.

**ELECTRICAL CHARACTERISTICS**

$V_{CC} = 3.6\text{ V}$ ,  $V_{DD} = 1.85\text{ V}$

Notes:  $T_a = 25^{\circ}\text{C} \pm 2^{\circ}\text{C}$  unless otherwise noted.

Parameter	Symbol	Condition	Limits			Unit	Note
			Min	Typ	Max		
<b>Circuit Current</b>							
Circuit Current (1) OFF Mode	$I_{CC1}$	NRST = 0 V	—	0	1	$\mu\text{A}$	—
Circuit Current (2) OFF Mode	$I_{CC2}$	NRST = 3.6V	—	250	500	$\mu\text{A}$	—
<b>Internal Oscillator</b>							
Oscillation Frequency	FDC1	$V_{CC} = 3.6\text{ V}$	1.92	2.40	2.88	MHz	—
<b>SCAN Switch</b>							
Switch On Resistance	RSCAN	$V_{CC} = 3.6\text{ V}$ $I_{Z1-Z7} = -20\text{ mA}$	—	1.5	3	$\Omega$	—
<b>Constant Voltage Source (LDO)</b>							
Output voltage (1)	$V_{L1}$	$I_{LDO} = -10\ \mu\text{A}$	2.75	2.85	2.95	V	—
Output voltage (2)	$V_{L2}$	$I_{LDO} = -15\text{ mA}$	2.75	2.85	2.95	V	—
<b>CLKIO</b>							
High Level Input Voltage Range	$V_{IH1}$	High Level Acknowledged Voltage (At External CLK Input Mode)	$0.7 \times V_{DD}$	—	$V_{DD} + 0.3$	V	—
Low Level Input Voltage Range	$V_{IL1}$	Low Level Acknowledged Voltage (At External CLK Input Mode)	-0.3	—	$0.3 \times V_{DD}$	V	—
High Level Output Voltage	$V_{OH1}$	$I_{CLKIO} = -1\text{ mA}$ (At Internal CLK Output Mode)	$0.8 \times V_{DD}$	—	$V_{DD} + 0.3$	V	—
Low Level Output Voltage	$V_{OL1}$	$I_{CLKIO} = 1\text{ mA}$ (At Internal CLK Output Mode)	-0.3	—	$0.2 \times V_{DD}$	V	—
High Level input Current	$I_{IH1}$	$V_{CC} = 5.5\text{ V}$ $V_{CLKIO} = 5.5\text{ V}$	-1	0	1	$\mu\text{A}$	—
Low Level input Current	$I_{IL1}$	$V_{CC} = 5.5\text{ V}$ $V_{CLKIO} = 0\text{ V}$	-1	0	1	$\mu\text{A}$	—

**ELECTRICAL CHARACTERISTICS (Continued)**

$V_{CC} = 3.6\text{ V}$ ,  $V_{DD} = 1.85\text{ V}$

Notes:  $T_a = 25^{\circ}\text{C} \pm 2^{\circ}\text{C}$  unless otherwise noted.

Parameter	Symbol	Condition	Limits			Unit	Note
			Min	Typ	Max		
<b>Constant Current Source (Matrix LED)</b>							
Output Current (1)	$I_{MX1}$	LED Current Setting = 20 mA $I_{MAX} = [011]$ , BRTXX = [1010] $V_{Z1-Z7} = 1\text{ V}$	19	20	21	mA	*1
DAC Current Step	DACSTEP	DAC Constant Current Mode LED Current Setting = 20 mA $I_{MAX} = [011]$ , BRTXX = [1010] $V_{Z1-Z7} = 1\text{ V}$ , IDAC1 = $I_{Z1-Z7}$ LED Current Setting = 22 mA $I_{MAX} = [011]$ , BRTXX = [1011] $V_{Z1-Z7} = 1\text{ V}$ , IDAC2 = $I_{Z1-Z7}$ DACSTEP = IDAC2 – IDAC1	0	2	4	mA	*2
OFF Mode Leak Current1	$I_{MXOFF1}$	$V_{CC} = 5.5\text{ V}$ , $V_{DD} = 5.5\text{ V}$ MTXON = 0 $V_{Z1-Z7} = 5.5\text{ V}$	-1	—	1	$\mu\text{A}$	*3
OFF Mode Leak Current2	$I_{MXOFF2}$	$V_{CC} = 5.5\text{ V}$ , $V_{DD} = 5.5\text{ V}$ MTXON = 0 $V_{Z1-Z7} = 0\text{ V}$	-1	—	1	$\mu\text{A}$	*3
Channel Difference	$I_{MXCH}$	LED Current Setting = 20 mA $I_{MAX} = [011]$ , BRTXX = [1010] Difference of Z1 to 7 current from the average current value	-5	—	5	%	—
<b>Voltage at which LED driver can keep constant current value</b>							
LED Driver Voltage	$V_{LD2}$	LED Current Setting = 20 mA $I_{MAX} = [011]$ , BRTXX = [1010] Voltage at which LED Current change within $\pm 5\%$ compared with LED Current of pin voltage = 0.5 V.	0.4	—	—	V	—

Note: \* 1: This is allowable value when recommended parts (ERJ2RHD393X) are used for the terminal IREF.

\* 2: Current step for individual channels (Z1~Z7).

\* 3: Please refer to page 18 for more information on the setting.



**ELECTRICAL CHARACTERISTICS (Continued)**

$V_{CC} = 3.6\text{ V}, V_{DD} = 1.85\text{ V}$

Notes:  $T_a = 25^{\circ}\text{C} \pm 2^{\circ}\text{C}$  unless otherwise noted.

Parameter	Symbol	Condition	Limits			Unit	Note
			Min	Typ	Max		
<b>SLAVSEL</b>							
High Level Input Voltage Range	$V_{IH2}$	High Level Acknowledged Voltage	$0.7 \times V_{DD}$	—	$V_{DD} + 0.3$	V	—
Low Level Input Voltage Range	$V_{IL2}$	Low Level Acknowledged Voltage	-0.3	—	$0.3 \times V_{DD}$	V	—
High Level Input Current	$I_{IH2}$	$V_{CC} = 5.5\text{ V}$ $V_{SLAVSEL} = 5.5\text{ V}$	-1	0	1	$\mu\text{A}$	—
Low Level Input Current	$I_{IL2}$	$V_{CC} = 5.5\text{ V}$ $V_{SLAVSEL} = 0\text{ V}$	-1	0	1	$\mu\text{A}$	—
<b>NRST</b>							
High Level Input Voltage Range	$V_{IH3}$	High Level Acknowledged Voltage	1.5	—	$V_{CC} + 0.3$	V	—
Low Level Input Voltage Range	$V_{IL3}$	Low Level Acknowledged Voltage	-0.3	—	0.6	V	—
High Level Input Current	$I_{IH3}$	$V_{CC} = 5.5\text{ V}$ $V_{NRST} = 5.5\text{ V}$	-1	0	1	$\mu\text{A}$	—
Low Level Input Current	$I_{IL3}$	$V_{CC} = 5.5\text{ V}$ $V_{NRST} = 0\text{ V}$	-1	0	1	$\mu\text{A}$	—
<b>I<sup>2</sup>C bus (Internal I/O stage characteristics)</b>							
Low-level input voltage	$V_{IL}$	Voltage which recognized that SDA and SCL are Low-level	-0.5	—	$0.3 \times V_{DD}$	V	*4
High-level input voltage	$V_{IH}$	Voltage which recognized that SDA and SCL are High-level	$0.7 \times V_{DD}$	—	$V_{DD_{MAX}} + 0.5$	V	*4
Low-level output voltage 1	$V_{OL1}$	$V_{DD} > 2\text{ V}$ $I_{SDA} = 3\text{ mA}$	0	—	0.4	V	—
Low-level output voltage 2	$V_{OL2}$	$V_{DD} < 2\text{ V}$ $I_{SDA} = 3\text{ mA}$	0	—	$0.2 \times V_{DD}$	V	—
Low-level output current	$I_{OL}$	$V_{SDA} = 0.4\text{ V}$	20	—	—	mA	—
Input current each I/O pin	$I_i$	$V_{CC} = 5.5\text{ V}, V_{DD} = 5.5\text{ V}$ $V_{SCL}, V_{SDA} = 0.1 V_{DD_{MAX}}$ to $0.9 V_{DD_{MAX}}$	-10	0	10	$\mu\text{A}$	—
SCL clock frequency	$f_{SCL}$	—	0	—	1 000	kHz	—

Note:  $V_{DD_{MAX}}$  refers to the maximum operating supply voltage of  $V_{DD}$ .

\*4 : The input threshold voltage of I<sup>2</sup>C bus ( $V_{th}$ ) is linked to  $V_{DD}$  (I<sup>2</sup>C bus I/O stage supply voltage).

In case the pull-up voltage is not  $V_{DD}$ , the threshold voltage ( $V_{th}$ ) is fixed to  $((V_{DD} / 2) \pm (\text{Schmitt width}) / 2)$  and High-level, Low-level of input voltage are not specified.

In this case, pay attention to Low-level (max.) value ( $V_{IL_{MAX}}$ ).

It is recommended that the pull-up voltage of I<sup>2</sup>C bus is set to the I<sup>2</sup>C bus I/O stage supply voltage ( $V_{DD}$ ).

**ELECTRICAL CHARACTERISTICS (Continued)**

$V_{CC} = 3.6\text{ V}, V_{DD} = 1.85\text{ V}$

Notes:  $T_a = 25^{\circ}\text{C} \pm 2^{\circ}\text{C}$  unless otherwise noted.

Parameter	Symbol	Condition	Limits			Unit	Note
			Min	Typ	Max		
<b>TSD (Thermal shutdown protection circuit)</b>							
Detection temperature	Tdet	Temperature which Constant current circuit, and Matrix SW turn off.	—	150	—	°C	*5 *6
<b>Constant Voltage Source (LDO)</b>							
Ripple rejection ratio (1)	PSL11	$V_{CC} = 3.6\text{ V} + 0.3\text{ V [p-p]}$ $f = 1\text{ kHz}$ $I_{LDO} = -15\text{ mA}$ $PSL11 = 20 \log (acV_{LDO} / 0.3)$	—	-50	—	dB	*6
Ripple rejection ratio (2)	PSL12	$V_{CC} = 3.6\text{ V} + 0.3\text{ V [p-p]}$ $f = 10\text{ kHz}$ $I_{LDO} = -15\text{ mA}$ $PSL12 = 20 \log (acV_{LDO} / 0.3)$	—	-40	—	dB	*6
Short-circuit protection current	IPT1	$V_{LDO} = 0\text{ V}$	—	40	—	mA	*6
<b>I<sup>2</sup>C bus (Internal I/O stage characteristics) (Continued)</b>							
Hysteresis of Schmitt trigger input 1	$V_{hys1}$	$V_{DD} > 2\text{ V}$ , Hysteresis of SDA, SCL	$0.05 \times V_{DD}$	—	—	V	*7 *8
Hysteresis of Schmitt trigger input 2	$V_{hys2}$	$V_{DD} < 2\text{ V}$ , Hysteresis of SDA, SCL	$0.1 \times V_{DD}$	—	—	V	*7 *8
Output fall time from $V_{IHmin}$ to $V_{ILmax}$	$t_{of}$	Bus capacitance :10pF to 550pF $I_p \leq 20\text{ mA} (V_{OLmax} = 0.4\text{ V})$ $I_p$ : Max. sink current	—	—	120	ns	*7 *8
Pulse width of spikes which must be suppressed by the input filter	$t_{SP}$	—	0	—	50	ns	*7 *8
Capacitance for each I/O pin	$C_i$	—	—	—	10	pF	*7 *8

Note: \*5 : Constant current circuit, and Matrix SW turn off and IC reset when TSD operates.

\*6 : Typical Design Value

\*7 : The timing of Fast-mode Plus devices in I<sup>2</sup>C-bus is specified in page 10. All values referred to  $V_{IHmin}$  and  $V_{ILmax}$  level.

\*8 : These are values checked by design but not production tested.

**ELECTRICAL CHARACTERISTICS (Continued)**

$V_{CC} = 3.6\text{ V}$ ,  $V_{DD} = 1.85\text{ V}$

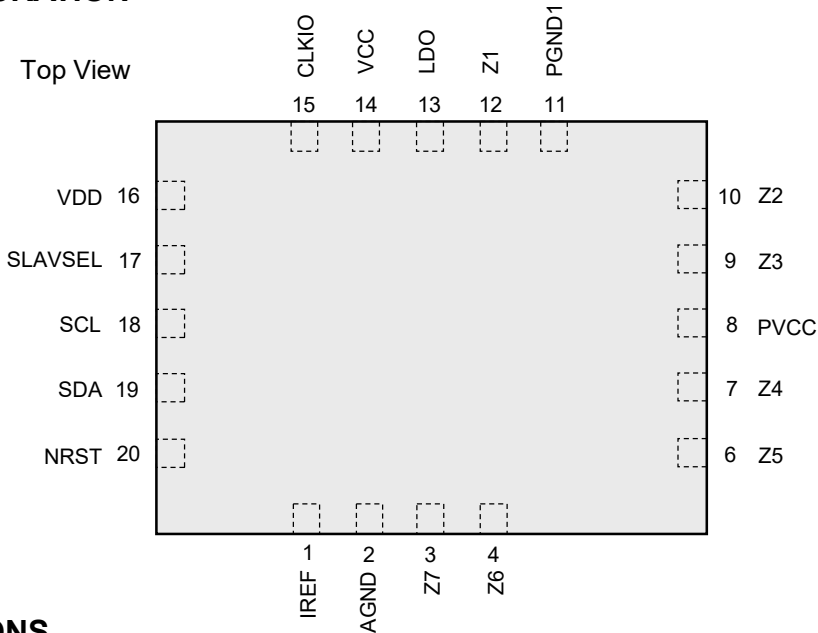
Notes:  $T_a = 25^{\circ}\text{C} \pm 2^{\circ}\text{C}$  unless otherwise noted.

Parameter	Symbol	Condition	Limits			Unit	Note
			Min	Typ	Max		
<b>I<sup>2</sup>C bus (Bus line specifications) (Continue)</b>							
Hold time (repeated) START condition	$t_{HD:STA}$	The first clock pulse is generated after $t_{HD:STA}$ .	0.26	—	—	$\mu\text{s}$	*7 *8
Low period of the SCL clock	$t_{LOW}$	—	0.5	—	—	$\mu\text{s}$	*7 *8
High period of the SCL clock	$t_{HIGH}$	—	0.26	—	—	$\mu\text{s}$	*7 *8
Set-up time for a repeat START condition	$t_{SU:STA}$	—	0.26	—	—	$\mu\text{s}$	*7 *8
Data hold time	$t_{HD:DAT}$	—	0	—	—	$\mu\text{s}$	*7 *8
Data set-up time	$t_{SU:DAT}$	—	50	—	—	ns	*7 *8
Rise time of both SDA and SCL signals	$t_r$	—	—	—	120	ns	*7 *8
Fall time of both SDA and SCL signals	$t_f$	—	—	—	120	ns	*7 *8
Set-up time of STOP condition	$t_{SU:STO}$	—	0.26	—	—	$\mu\text{s}$	*7 *8
Bus free time between STOP and START condition	$t_{BUF}$	—	0.5	—	—	$\mu\text{s}$	*7 *8
Capacitive load for each bus line	$C_b$	—	—	—	550	pF	*7 *8
Data valid time	$t_{VD:DAT}$	—	—	—	0.45	$\mu\text{s}$	*7 *8
Data valid acknowledge	$t_{VD:ACK}$	—	—	—	0.45	$\mu\text{s}$	*7 *8
Noise margin at the Low-level for each connected device	$V_{nL}$	—	$0.1 \times V_{DD}$	—	—	V	*7 *8
Noise margin at the High-level for each connected device	$V_{nH}$	—	$0.2 \times V_{DD}$	—	—	V	*7 *8

Note: \*7 : The timing of Fast-mode Plus devices in I<sup>2</sup>C-bus is specified in page 10. All values referred to  $V_{IHMIN}$  and  $V_{ILMAX}$  level.

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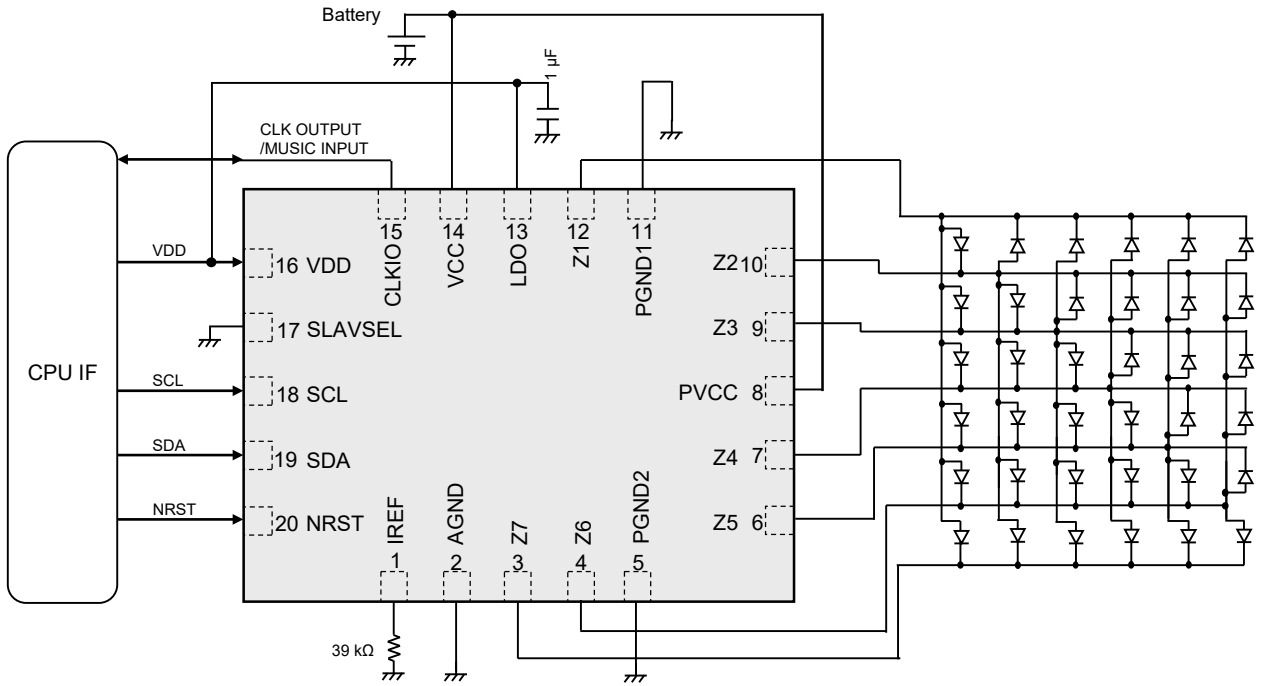
**PIN CONFIGURATION**



**PIN FUNCTIONS**

Pin No.	Pin name	Type	Description	Pin processing at unused
1	IREF	Output	Resistor connection pin for constant current setup	(Required pin)
2	AGND	Ground	Ground pin	(Required pin)
3	Z7	Output	Constant current circuit, PWM control output pin, Control switch pin for matrix driver	Open
4	Z6	Output	Constant current circuit, PWM control output pin, Control switch pin for matrix driver	Open
5 11	PGND2 PGND1	Ground	Power Ground pin	(Required pin)
6	Z5	Output	Constant current circuit, PWM control output pin, Control switch pin for matrix driver	Open
7	Z4	Output	Constant current circuit, PWM control output pin, Control switch pin for matrix driver	Open
8	PVCC	Power supply	Power supply for matrix driver	Battery or External power supply
9	Z3	Output	Constant current circuit, PWM control output pin, Control switch pin for matrix driver	Open
10	Z2	Output	Constant current circuit, PWM control output pin, Control switch pin for matrix driver	Open
12	Z1	Output	Constant current circuit, PWM control output pin, Control switch pin for matrix driver	Open
13	LDO	Output	LDO output pin	(Required pin)
14	VCC	Power supply	Power supply for Internal reference circuit	Battery or External power supply
15	CLKIO	Input/Output	Reference clock input output / Music Input pin	Open
16	VDD	Power supply	Power supply for I <sup>2</sup> C interface	(Required pin)
17	SLAVSEL	Input	Slave address selection pin for I <sup>2</sup> C interface	(Required pin)
18	SCL	Input	Clock input pin for I <sup>2</sup> C interface	(Required pin)
19	SDA	Input/Output	Data input / output pin for I <sup>2</sup> C interface	(Required pin)
20	NRST	Input	Reset input pin	(Required pin)

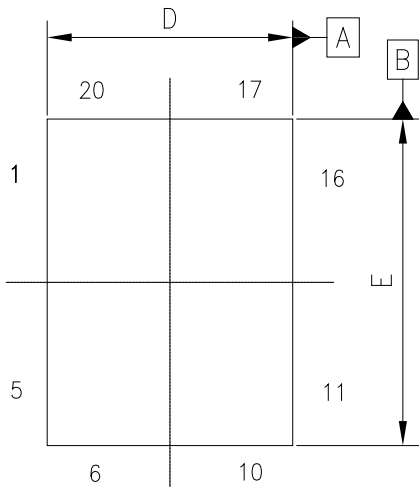
RECOMMENDED CIRCUIT



Note: The recommended circuit is an example. The operation of the mass production set is not guaranteed. Sufficient evaluation and verification is required in the design of the mass production set. Customer is fully responsible for the incorporation of the above illustrated application circuit in the production.

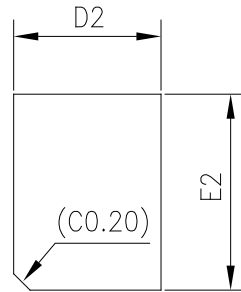
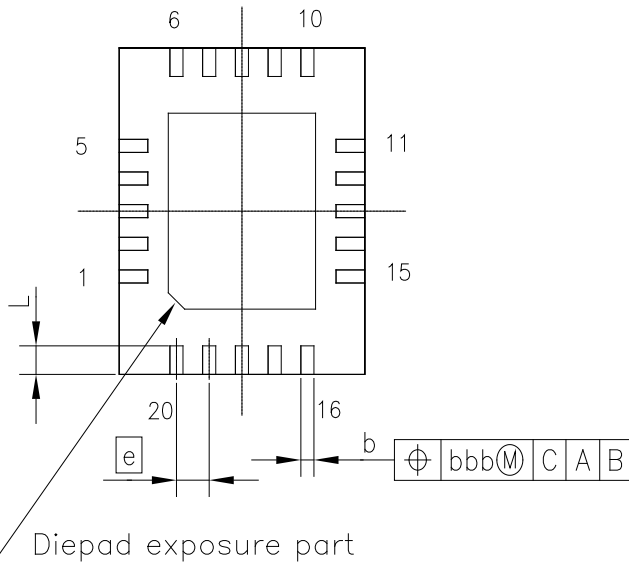
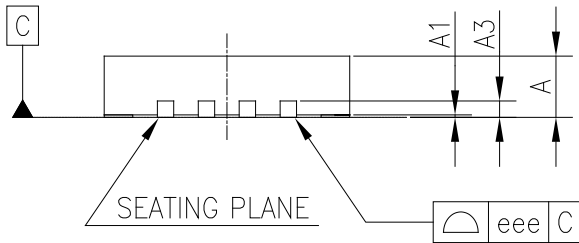
**PACKAGE INFORMATION**

QFN 20L 3x4mm<sup>2</sup>, Thickness 0.8mm, Lead Pitch 0.4mm, Lead Length 0.35mm, EP Size 1.8x2.6mm



VARIATIONS (ALL DIMENSIONS SHOWN IN MM)

SYMBOLS	MIN.	NOM.	MAX.
A	-	-	0.80
A1	0.00	-	0.05
A3	0.20REF		
D	2.90	3.00	3.10
D2	1.70	1.80	1.90
E	3.90	4.00	4.10
E2	2.50	2.60	2.70
L	0.25	0.35	0.45
b	0.11	0.16	0.21
e	0.40BSC		
bbb	0.07		
eee	0.08		



Diepad exposure part

**USAGE NOTES**

1. Pay attention to the direction of IC. When mounting it in the wrong direction onto the PCB (printed-circuit-board), it might emit smoke or ignite.
2. Pay attention in the PCB (printed-circuit-board) pattern layout in order to prevent damage due to short circuit between pins. In addition, refer to the Pin Description for the pin configuration.
3. Perform visual inspection on the PCB before applying power, otherwise damage might happen due to problems such as solder-bridge between the pins of the semiconductor device. Also, perform full technical verification on the assembly quality, because the same damage possibly can happen due to conductive substances, such as solder ball, that adhere to the IC during transportation.
4. Take notice in the use of this product that it might be damaged or occasionally emit smoke when an abnormal state occurs such as output pin-VCC short (Power supply fault), output pin-GND short (Ground fault), or output-to-output-pin short (load short). Safety measures such as installation of fuses are recommended because the extent of the above-mentioned damage and smoke emission will depend on the current capability of the power supply.
5. The protection circuit is for maintaining safety against abnormal operation. Therefore, the protection circuit should not work during normal operation.  
Especially for the thermal protection circuit, if the area of safe operation or the absolute maximum rating is momentarily exceeded due to output pin to VCC short (Power supply fault), or output pin to GND short (Ground fault), the IC might be damaged before the thermal protection circuit could operate.
6. Unless specified in the product specifications, make sure that negative voltage or excessive voltage are not applied to the pins because the device might be damaged, which could happen due to negative voltage or excessive voltage generated during the ON and OFF timing when the inductive load of a motor coil or actuator coils of optical pick-up is being driven.
7. The product which has specified ASO (Area of Safe Operation) should be operated in ASO.
8. Verify the risks which might be caused by the malfunctions of external components.

**Revision History**

Date	Revision	Description
2020.10.31	1.00	1. initially issued
2021.3.15	1.01	1. Modify $\theta_{JA}$ , $P_D$ (P4) 2. Modify pin configuration (P12)
2021.12.21	1.02	1. Added important notice on page2 2. Remove important notice page from previous version page 49



## Important Notice

Nuvoton Products are neither intended nor warranted for usage in systems or equipment, any malfunction or failure of which may cause loss of human life, bodily injury or severe property damage. Such applications are deemed, "Insecure Usage".

Insecure usage includes, but is not limited to: equipment for surgical implementation, atomic energy control instruments, airplane or spaceship instruments, the control or operation of dynamic, brake or safety systems designed for vehicular use, traffic signal instruments, all types of safety devices, and other applications intended to support or sustain life.

All Insecure Usage shall be made at customer's risk, and in the event that third parties lay claims to Nuvoton as a result of customer's Insecure Usage, customer shall indemnify the damages and liabilities thus incurred by Nuvoton.

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